



PATENT / DOCKET NO.: 24061.106 /TSMC2003-0551
CUSTOMER NO. 42717

INVENTOR'S DECLARATION FOR PATENT APPLICATION

As below named inventor, I hereby declare that:

Our residence, post office address and citizenship are as stated below next to our names;

I believe I are the original, first and sole joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled

SEMICONDUCTOR MANUFACTURING CAPACITY FEATURES EXCHANGE SYSTEM

the specification of which: (check one)

_____ is attached hereto.

 X was filed on March 26, 2004
under Attorney's Docket Number 24061.106 (TSMC2003-0551)
as Application Serial No. 10/809,985
and was amended on _____ (if applicable).

I hereby authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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PATENT / DOCKET NO.: 24061.106 / TSMC2003-0551
CUSTOMER NO. 27683

FULL NAME OF INVENTOR: Chung-Chien Fang

INVENTOR'S SIGNATURE: Chung-Chien Fang

DATED: Apr. 1, 2004

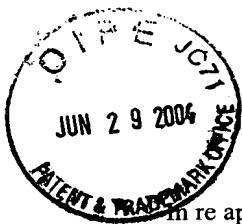
RESIDENCE: (city, country)

POST OFFICE ADDRESS: (address)
(city, country)

CITIZENSHIP: Taiwan, R.O.C.

R-70653.1

D-1205266.1



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

HB

In re application of:
Chung-Chien Fang

Serial No.: Unknown

Filed: Herewith

For: Semiconductor Manufacturing Capacity
Features Exchange System

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Attorney Docket No.: 24061.106
TSMC2003-0551

Customer No. 27683

Group Art Unit: Unknown

Examiner: Unknown

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

POWER OF ATTORNEY FOR PATENT APPLICATION

As a representative of the Assignee, Taiwan Semiconductor Manufacturing Company, Ltd., I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

David L. McCombs (Reg. No. 32,271); Jeffrey M. Becker (Reg. No. 35,442); James R. Bell (Reg. No. 26,528); Timothy F. Bliss (Reg. No. 50,925); Randall C. Brown (Reg. No. 31,213); Randall E. Colson (Reg. No. 40,566); Michael A. Davis, Jr. (Reg. No. 35,488); Andrew S. Ehmke (Reg. No. 50,271); Priscilla Ferguson (Reg. No. 42,531); Sarah T. Harris (Reg. No. 35,891); William E. Hickman (Reg. No. 46,771); David R. Hofman (Reg. No. P-55,727); Rita M. Irani (Reg. No. 31,028); Wei Wei Jeang (Reg. No. 33,305); Warren B. Kice (Reg. No. 22,732); J. Andrew Lowes (Reg. No. 40,706); Todd Mattingly (Reg. No. 40,298); Julie Nickols (Reg. No. 50,826); Gloria Norberg (Reg. No. 36,706); David M. O'Dell (Reg. No. 42,044); T. Murray Smith (Reg. No. 30,222) and Chien Wei Chou (Reg. No. 41,672).

Please address all correspondence and telephone calls regarding this application to:

David M. O'Dell
Attorney for Applicants
Haynes and Boone, LLP
901 Main Street, Suite 3100
Dallas, TX 75202-3789
972-739-8635 / 214-200-0853 - Fax

The undersigned is the representative for the Assignee of the entire right, title, and interest in the patent application identified above. A copy of the assignment or other documents in the chain of title are attached.

The undersigned (whose title is supplied below) is authorized to act on behalf of the Assignee.

Taiwan Semiconductor Manufacturing Company, Ltd.

Chien Wei Chou

Date

Chien-Wei Chou
Title: Director, IP Division

ASSIGNMENT

WHEREAS, I

Chung-Chien Fang

of

(address)
(city, country)

has invented certain improvements in

SEMICONDUCTOR MANUFACTURING CAPACITY FEATURES EXCHANGE SYSTEM

for which I have executed an application for Letters Patent of the United States of America,

	of even date filed herewith; and
X	filed on March 26, 2004 and assigned application number 10/809,985; and

WHEREAS, I authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

01-APR-2004

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04/02 '93 19:23 NO.166 02/03

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Patent / Docket No.: 24061.106/TSMC2003-0551
Customer No. 27683

Inventor Name: Chung-Chien Fang

Residence Address: (address)
Hsin-Chu, Taiwan 300, R.O.C.
Taiwan, R.O.C.

✓ Dated: Apr 1, 2004

✓ Chungchien Fang
Inventor Signature

R-70652.1

D-1205268

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